

ABSTRACT OF THE DISCLOSURE

[0029] An apparatus and method for forming a layer of underfill adhesive on an integrated circuit in wafer form is described. In one embodiment, the layer of underfill adhesive is disposed and partially cured on the active surface of the wafer. Once the underfill adhesive has cured, the wafer is singulated. The individual integrated circuits or die are then mounted onto a substrate such as a printed circuit board. When the solder balls of the integrated circuit are reflowed to form joints with corresponding contact pads on the substrate, the underfill adhesive is completely cured. In an alternative embodiment, the underfill adhesive is fully cured after it is disposed onto the active surface of the wafer.